Effective June 2017 Supersedes September 2012

FP1007R6 High frequency, high current power inductors



Product features

- 10.5 x 8.0 x 7.0mm Maximum surface mount package
- Ferrite core material
- Controlled DCR tolerance for sensing circuits
- Inductance Range from 150nH to 470nH
- Current range from 23.5 to 75 Amps
- Frequency range up to 2MHz
- Halogen free, lead free, RoHS compliant

Applications

- Multi-phase regulators
- Voltage Regulator Modules (VRMs)
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- · Graphics cards and battery power systems
- Point-of-Load modules
- DCR Sensing

Environmental data

- Storage temperature range (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature:
 J-STD-020 (latest revision) compliant





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5. Isat2: Peak current for approximately 20% rolloff at +100°C.

Δl (peak-to-peak ripple current in Amps). 7. Part Number Definition: FP1007R6-Rxx-R

Rxx= Inductance value in uH, R = decimal point

FP1007R6 = Product code and size

-R suffix = RoHS compliant

6. K-factor: Used to determine Bp-p for core loss (see graph). Bp-p = K * L

* ΔI * 10⁻³. Bp-p:(Gauss), K: (K-factor from table), L: (Inductance in nH),

			Product S	pecifications			
Part	OCL ¹ ±10%	FLL ² Min.	Irms ³	I _{sat} 1 ⁴ @25°C	Isat 2 ⁵ @100°C	DCR @20°C	
Number ⁷	(nH)	(nH)	(Amps)	(Amps)	(Amps)	(mΩ)	K-Factor ⁶
FP1007R6-R15-R	150	108		75.0	60.0		
FP1007R6-R18-R	180	129		60.0	50.0		
FP1007R6-R22-R	220	158	-	50.0	40.0	-	
FP1007R6-R27-R	270	194	61	41.0	33.0	0.29 ± 5%	348.8
FP1007R6-R33-R	330	237	-	33.0	26.5		
FP1007R6-R39-R	390	280	-	28.0	22.5		
FP1007R6-R47-R	470	338		23.5	19.0		

1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10Vrms, 0.0Adc

2. Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1Vrms, Isat1

3. I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

4. Isat1: Peak current for approximately 20% rolloff at +25°C.

Dimensions- mm



The nominal DCR is measured from point "A" to point "B"

Part Marking: 1007R6, Rxx = Inductance value in µH. (R = Decimal point) wwllyy = Date code R = Revision level Tolerance are

 ± 0.15 mm unless otherwise specified.

Soldering surfaces to be coplanar within 0.1016mm.

PCB tolerance ±0.1mm unless otherwise specified.

Packaging information - mm



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Temperature rise vs total loss



Core loss vs Bp-p







Solder Reflow Profile



Table 1 - Sta	able 1 - Standard SnPb Solder (T _C)				
	Volume	Volume			
Package	mm ³	mm ³			
Thickness	<350	≥350			
<2.5mm	235°C	220°C			
≥2.5mm	220°C	220°C			
Table 2 - Lea	ad (Pb) Fre	e Solder (T _C)			
Table 2 - Lea	ad (Pb) Fre Volume	e Solder (T _C) Volume	Volume		
Table 2 - Lea Package		· ·	Volume mm ³		
	Volume	Volume			
Package	Volume mm ³	Volume mm ³	mm ³		
Package Thickness	Volume mm ³ <350 260°C	Volume mm ³ 350 - 2000	mm ³ >2000		

Reference JDEC J-STD-020

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak	 Temperature min. (T_{smin}) 	100°C	150°C	
	 Temperature max. (T_{smax}) 	150°C	200°C	
	 Time (T_{smin} to T_{smax}) (t_s) 	60-120 Seconds	60-120 Seconds	
Average ramp up rate T _{smax} to T _p		3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL)		183°C	217°C	
Time at liquidous (t _L)		60-150 Seconds	60-150 Seconds	
Peak package body temperature (TP)*		Table 1	Table 2	
Time $(t_p)^{\star\star}$ within 5 °C of the specified classification temperature (T_c)		20 Seconds**	30 Seconds**	
Average ramp-down rate (Tp to Tsmax)		6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.	

 * Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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